

REMARKS/ARGUMENTS

Claims 1-4 have been amended.

Claims 1-4 have been rewritten.

5 Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendments. The attached page is captioned **"Version with markings to show changes made"**.

Applicant thinks that it is true that Hsieh does not disclose that a transparent layer is encapsulated on the memory chip and display the mark of memory chip.

10 Thus, the Applicant's Prior Art does not disclose a similar structure to that of this application, and does not motivate the Applicant to finish this application. Reconsideration of the Claims 1, and 4 are politely requested.

Applicant thinks that it is true that Chen does not disclose that a transparent small memory card. According to the examiner's opinion, please refer to 768,
15 patent Applicant's, which is shown a surface mounting method for high power light emitting diode shows a transparent resin or epoxy layer 130 encapsulating the LED chip 103 and substrate. The transparent layer is encapsulated on the chip for reflecting the light from the chip. The transparent layer is encapsulated on the chip to display the mark of the chip.

20 Thus, the 864, patent does not disclose a similar structure to that of this application, and does not motivate the Applicant to finish this application.

Reconsideration of the Claims 1 - 4 is politely requested.

Thank you for your consideration.

Respectfully submitted,

Date: 10/17, 05

Jichen WU

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